US0D1047884S

(12) United States Design Patent

Daigo et al.

(10) Patent No.: US D1,047,884 S
(45) Date of Patent: ** Oct. 22, 2024

(54) **SUSCEPTOR COVER**

(71) Applicant: **NuFlare Technology, Inc.**, Kanagawa (JP)

(72) Inventors: **Yoshiaki Daigo**, Yokohama (JP); **Takuto Umetsu**, Yokohama (JP)

(73) Assignee: **NuFlare Technology, Inc.**, Kanagawa (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/834,638**

(22) Filed: **Apr. 13, 2022**

(30) **Foreign Application Priority Data**

Oct. 22, 2021 (JP) ..... 2021-022982 D

(51) **LOC (14) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/101, 199, 182, 121, 154; D23/269, D23/209; D9/779, 419, 454, 520, 416; D3/302; D34/29; D4/137; D15/138, D15/144.1
CPC F16J 15/025; F16J 15/064; C25D 17/12; C25D 17/14; C25D 17/06; C25D 17/08; C25D 7/12; C25D 7/10; H01H 9/04; H01H 9/161; H01H 9/0214; H01H 9/02; H01H 13/04; H01H 13/06; H01H 13/023; H01H 21/08; H01H 19/025; H01L 21/283; H01L 21/68742; H01L 21/68735
See application file for complete search history.

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Primary Examiner — Mary Shannon Malley
Assistant Examiner — Ikeadi M Ndukwu
(74) *Attorney, Agent, or Firm* — Rankin, Hill & Clark LLP

(57) **CLAIM**

The ornamental design for a susceptor cover as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a susceptor cover showing our new design,
FIG. **2** is a front elevational view thereof,
FIG. **3** is a rear elevational view thereof,
FIG. **4** is a right side elevational view thereof,
FIG. **5** is a left side elevational view thereof,
FIG. **6** is a top plan view thereof, a bottom plan view being a mirror image thereof; and,
FIG. **7** is an enlarged end face sectional view taken along line **7-7** of FIG. **2**.
The broken lines in FIG. **2** are for the purpose of illustrating portions of the susceptor cover in FIG. **7** and form no part of the claimed design.

1 Claim, 6 Drawing Sheets

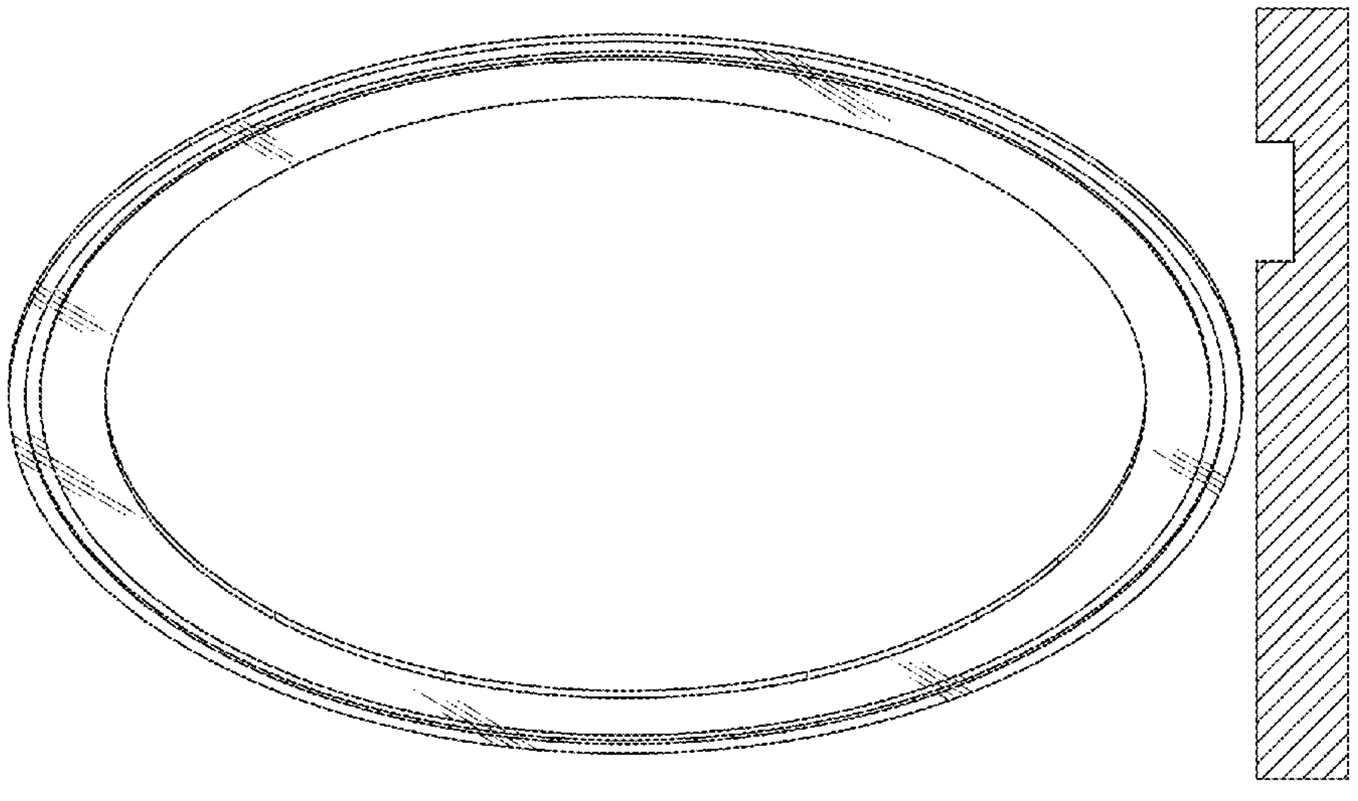

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FIG. 1

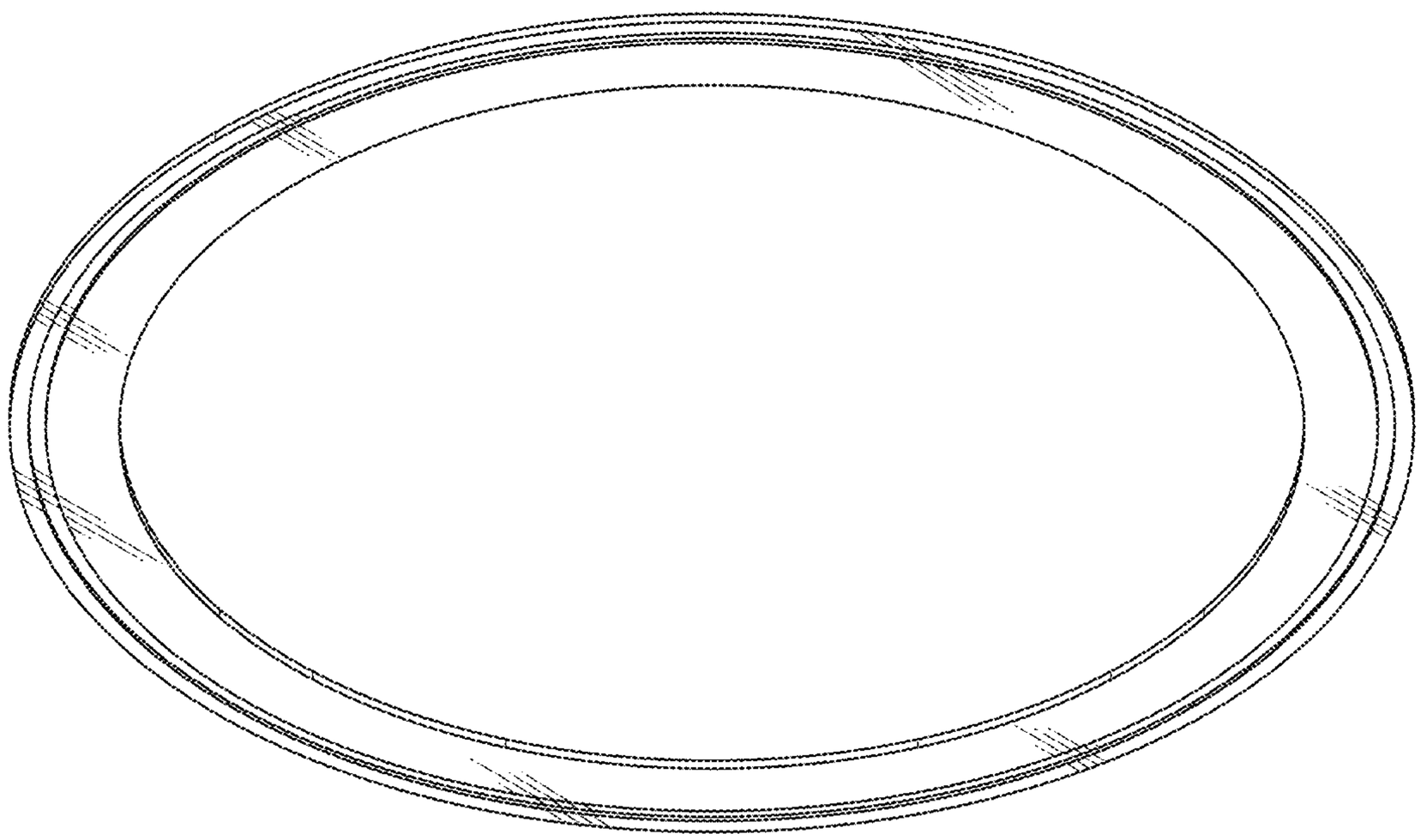

FIG. 2

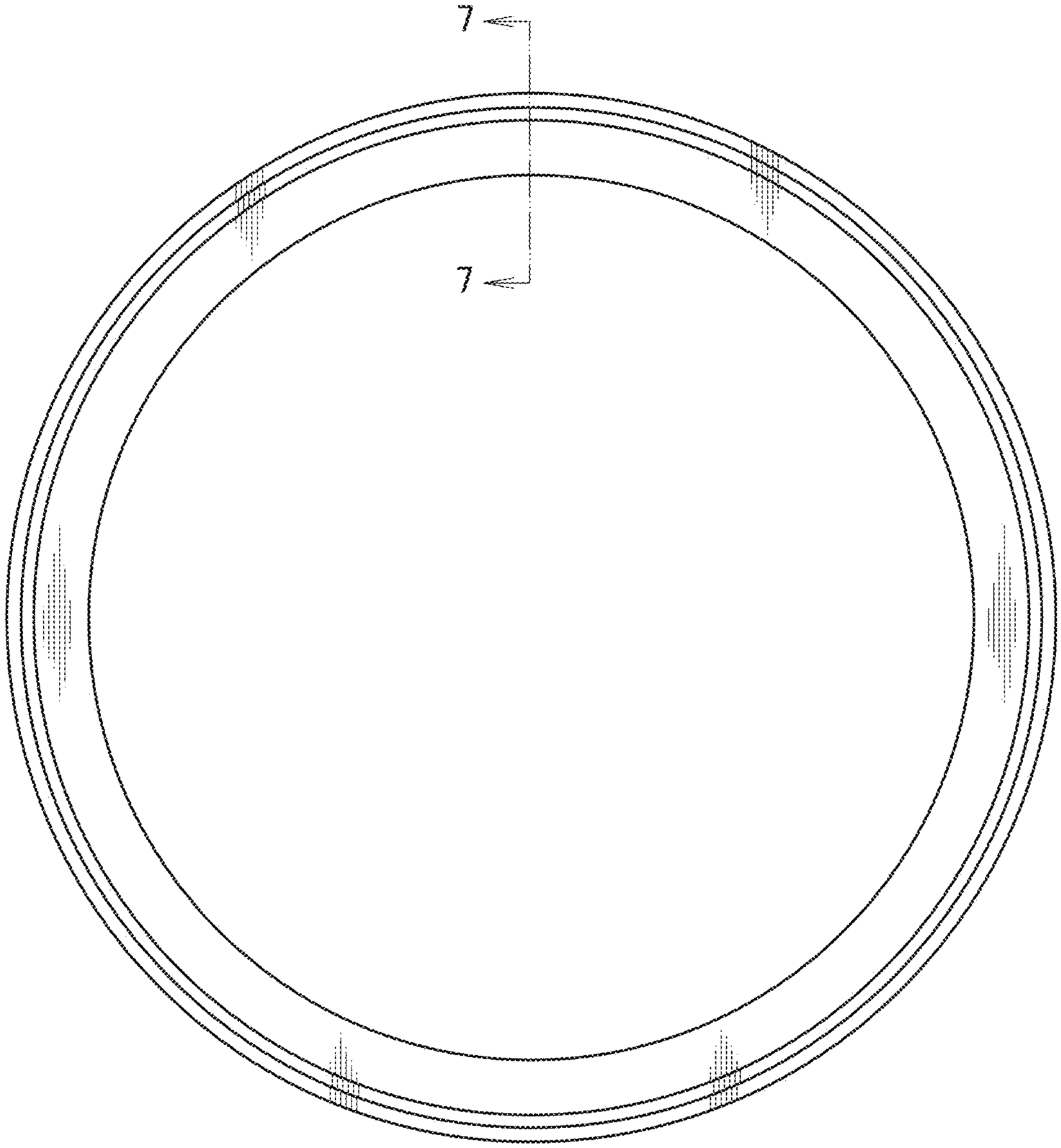

FIG. 3

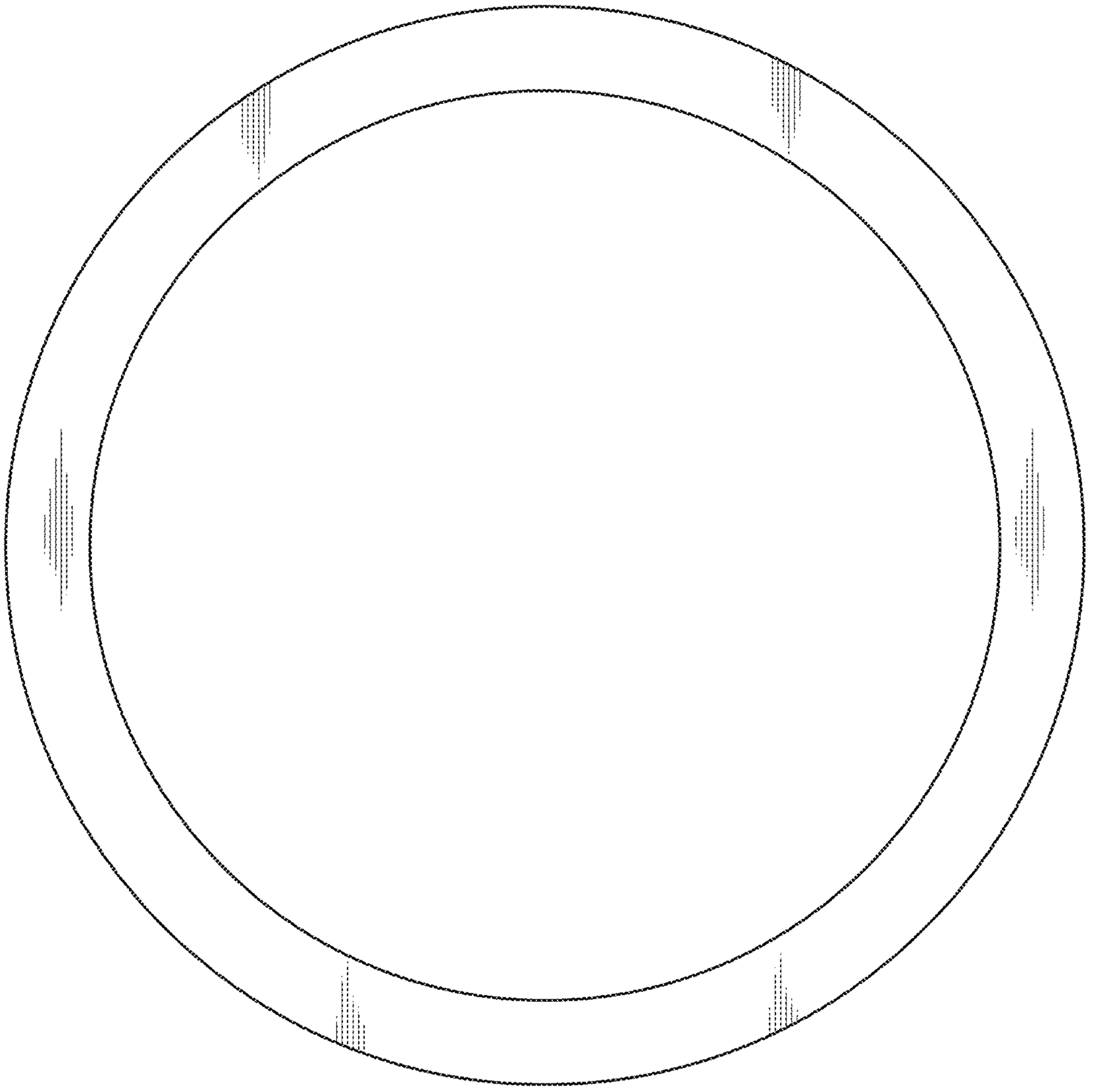

FIG. 4

FIG. 5

FIG. 6

FIG. 7